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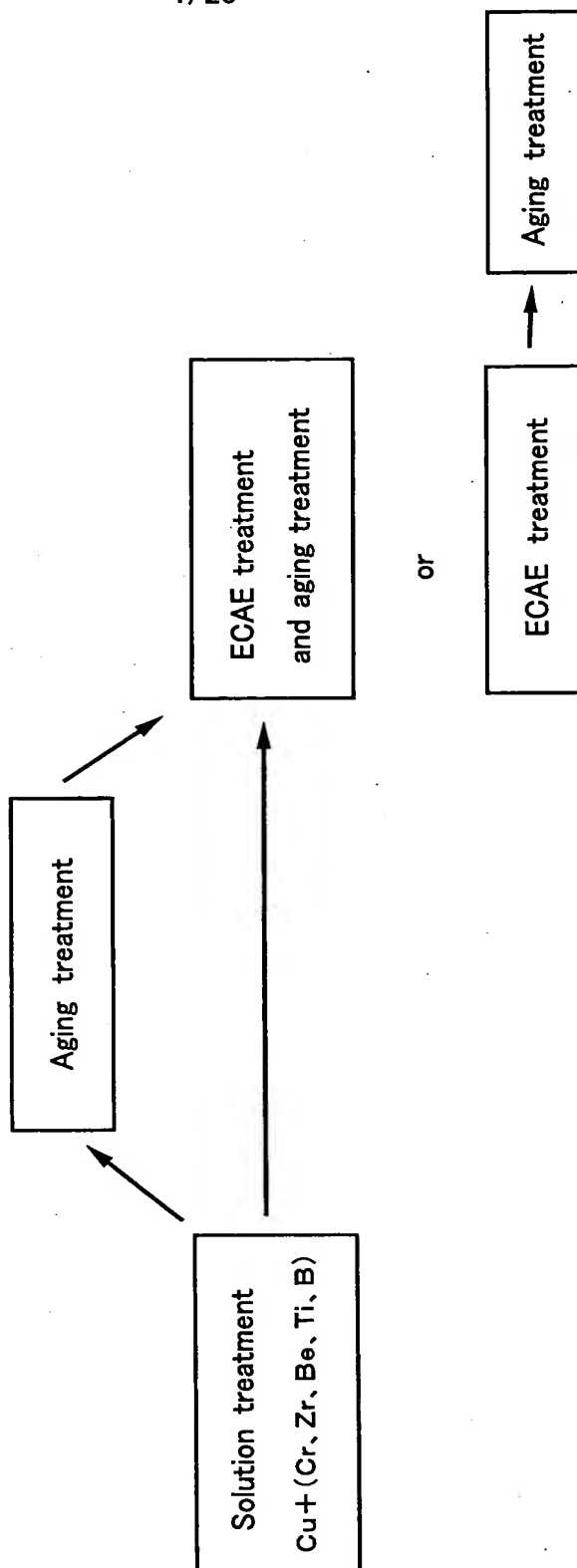


FIG. 1

FIG. 2

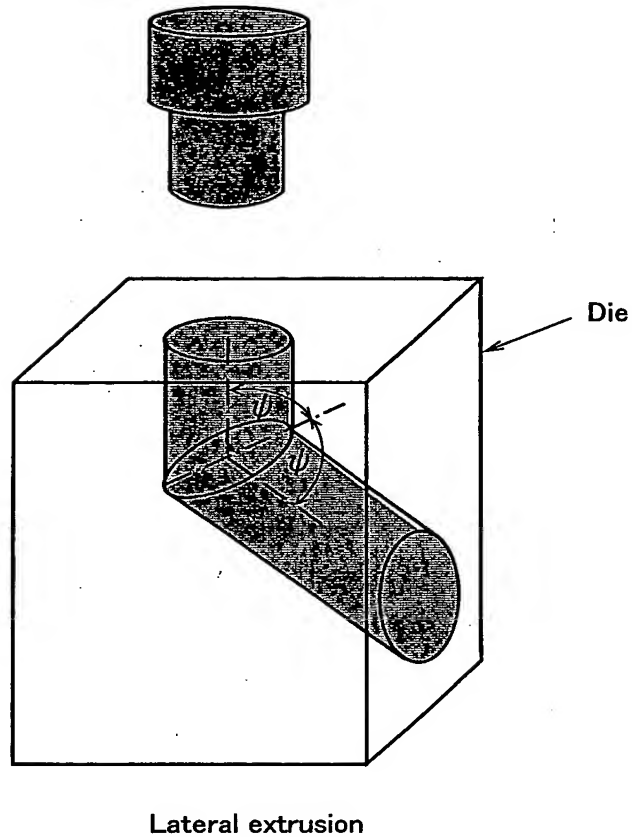
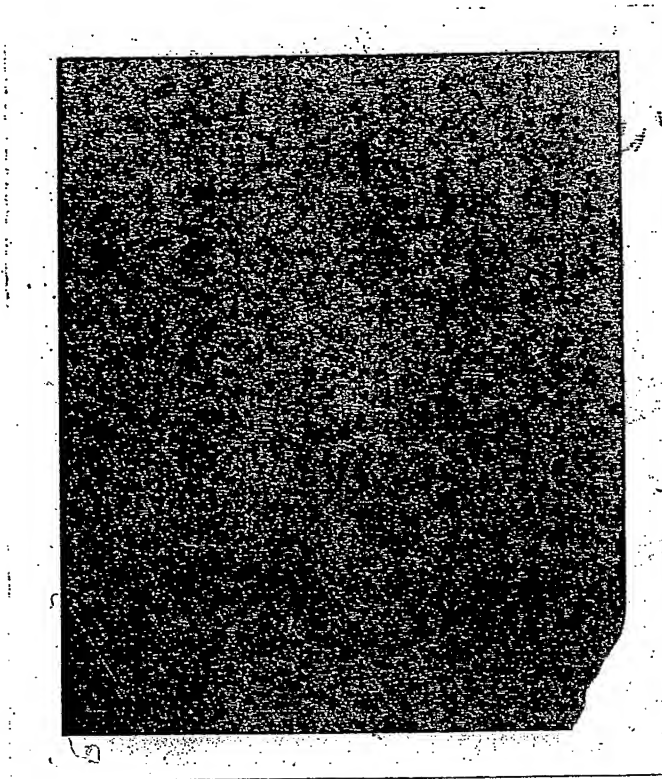
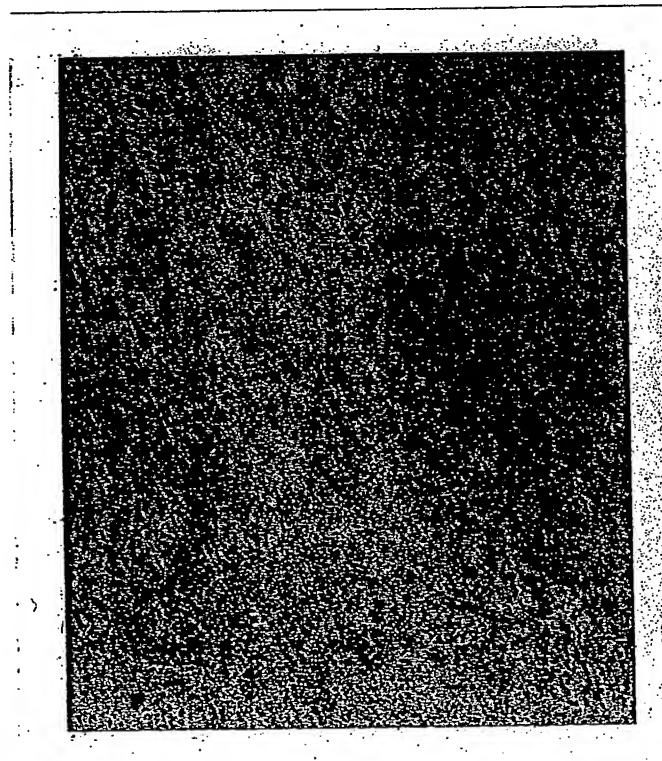


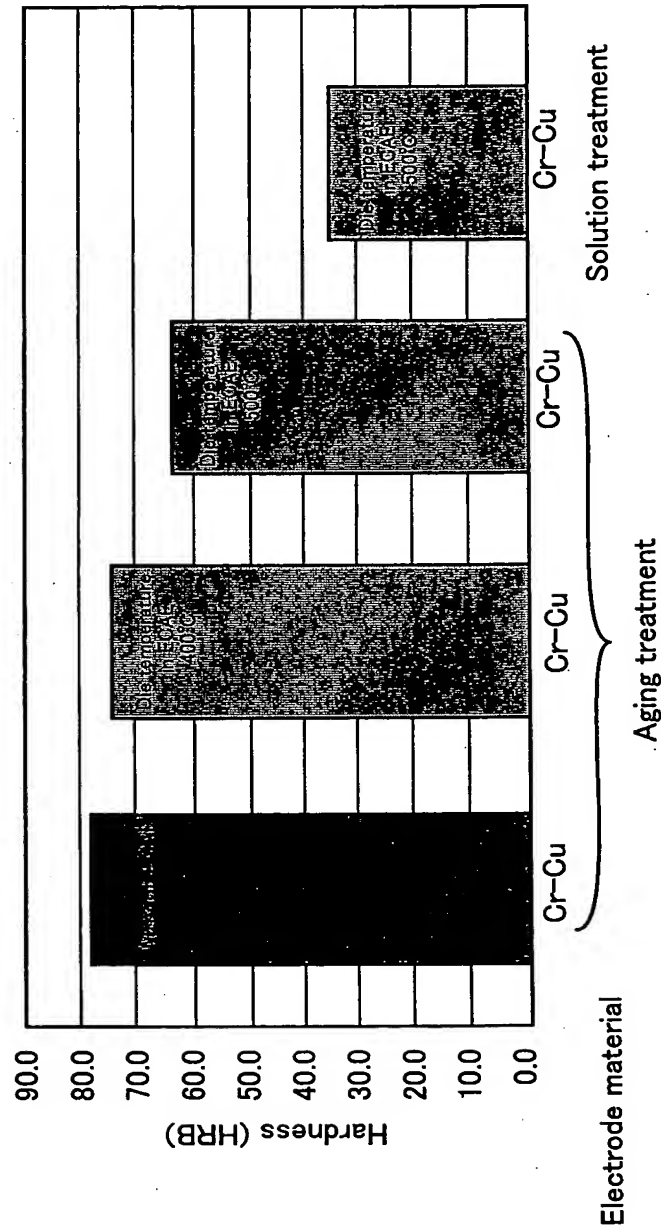
FIG. 3



(b)



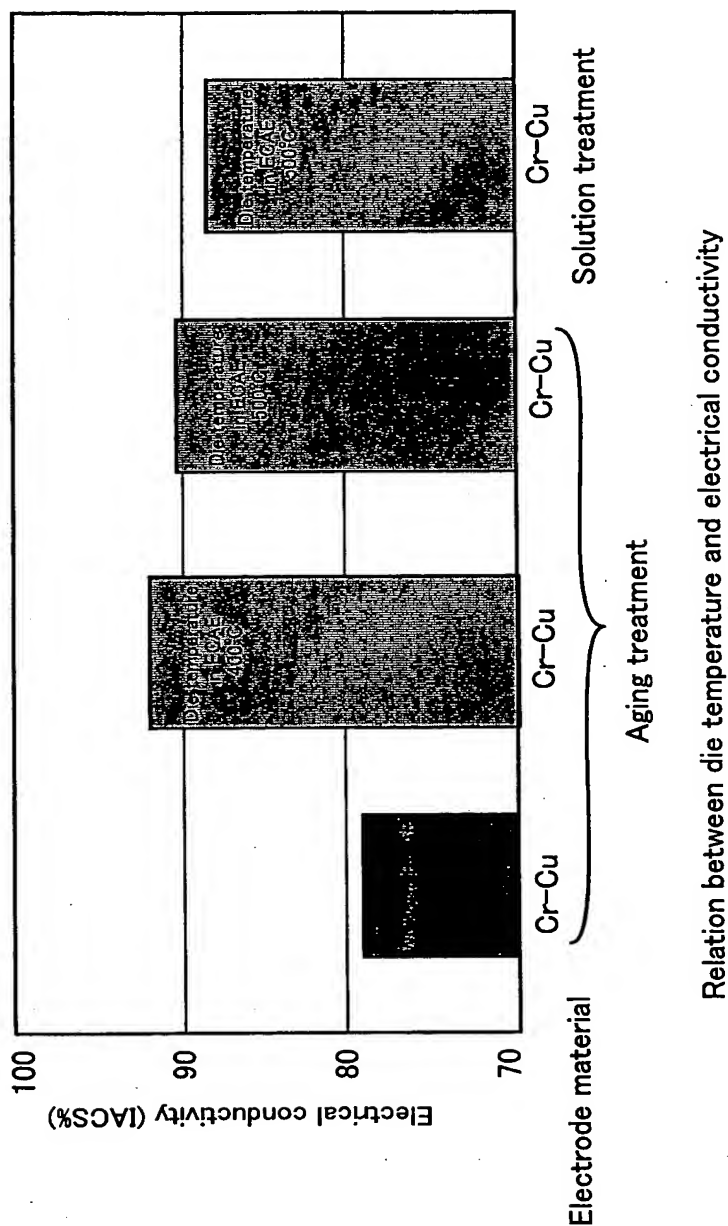
(a)



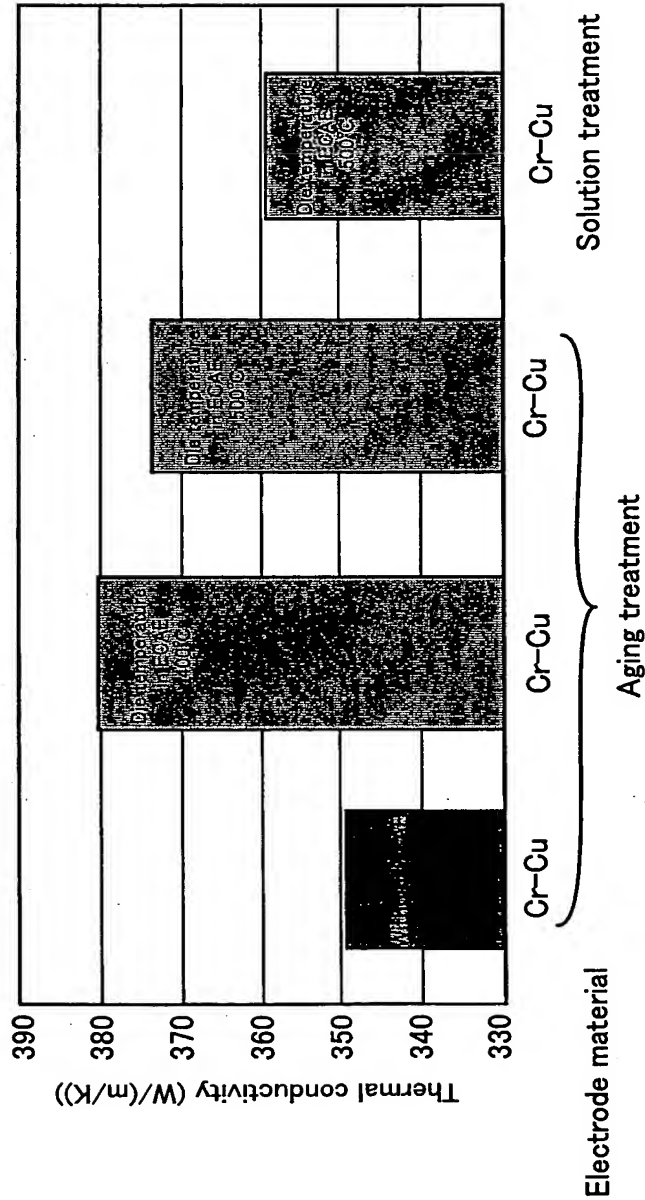
Relation between die temperature and hardness

FIG. 4

FIG. 5



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Relation between die temperature and thermal conductivity

FIG. 6

FIG. 7

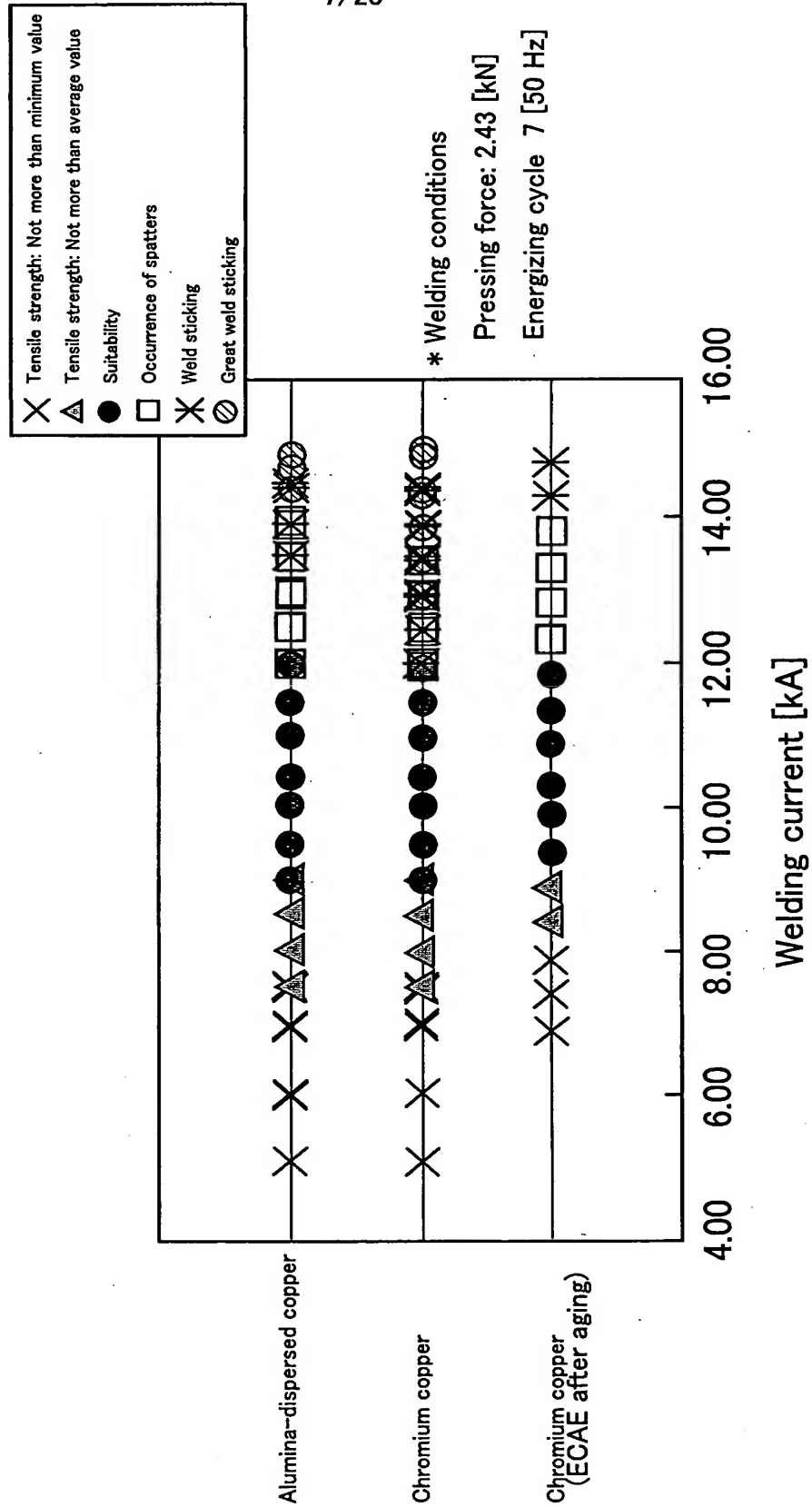
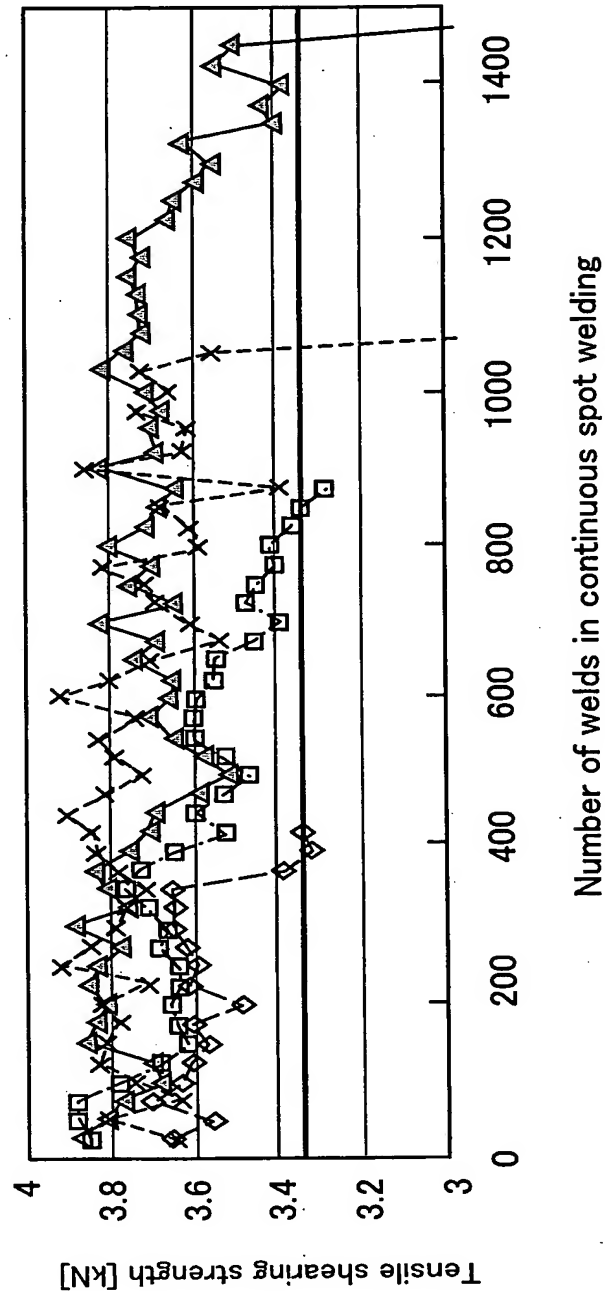
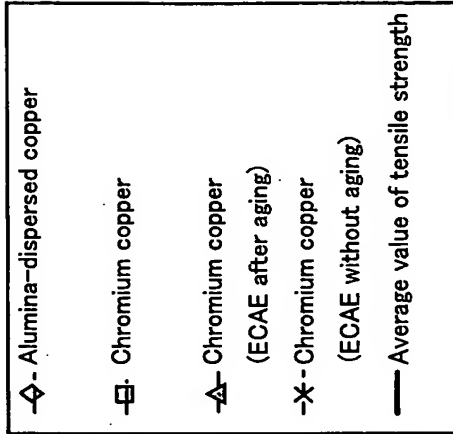


FIG. 8



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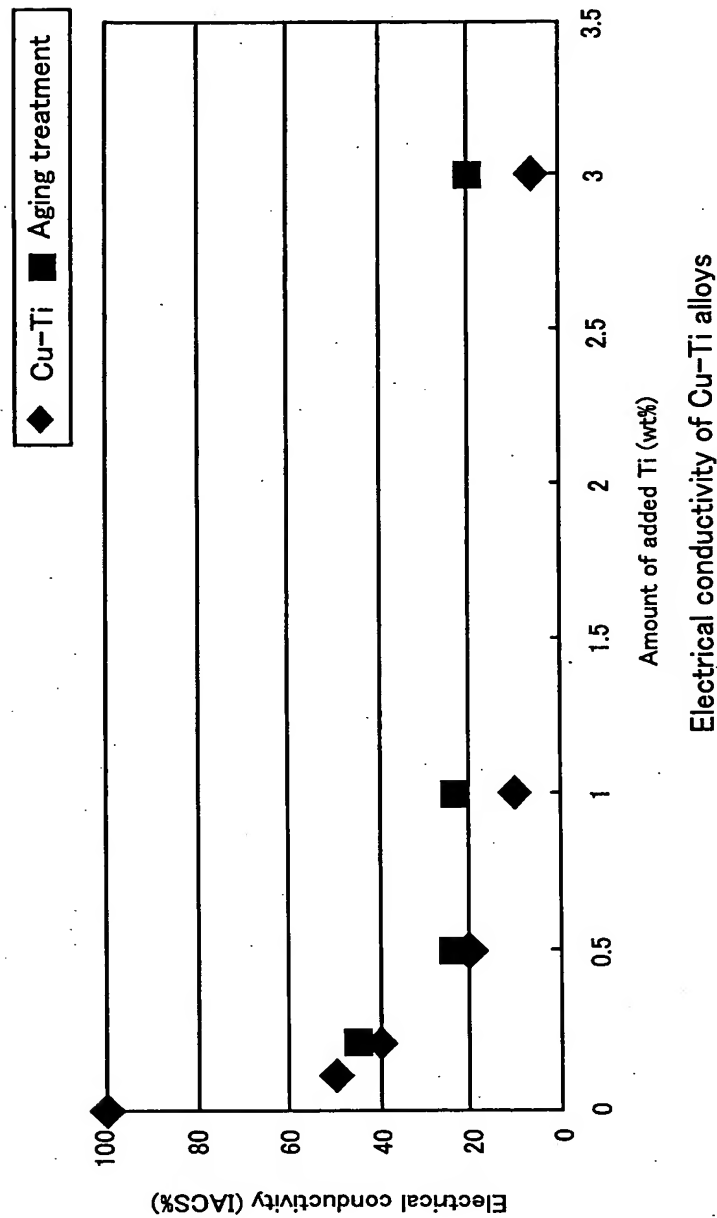


FIG. 9

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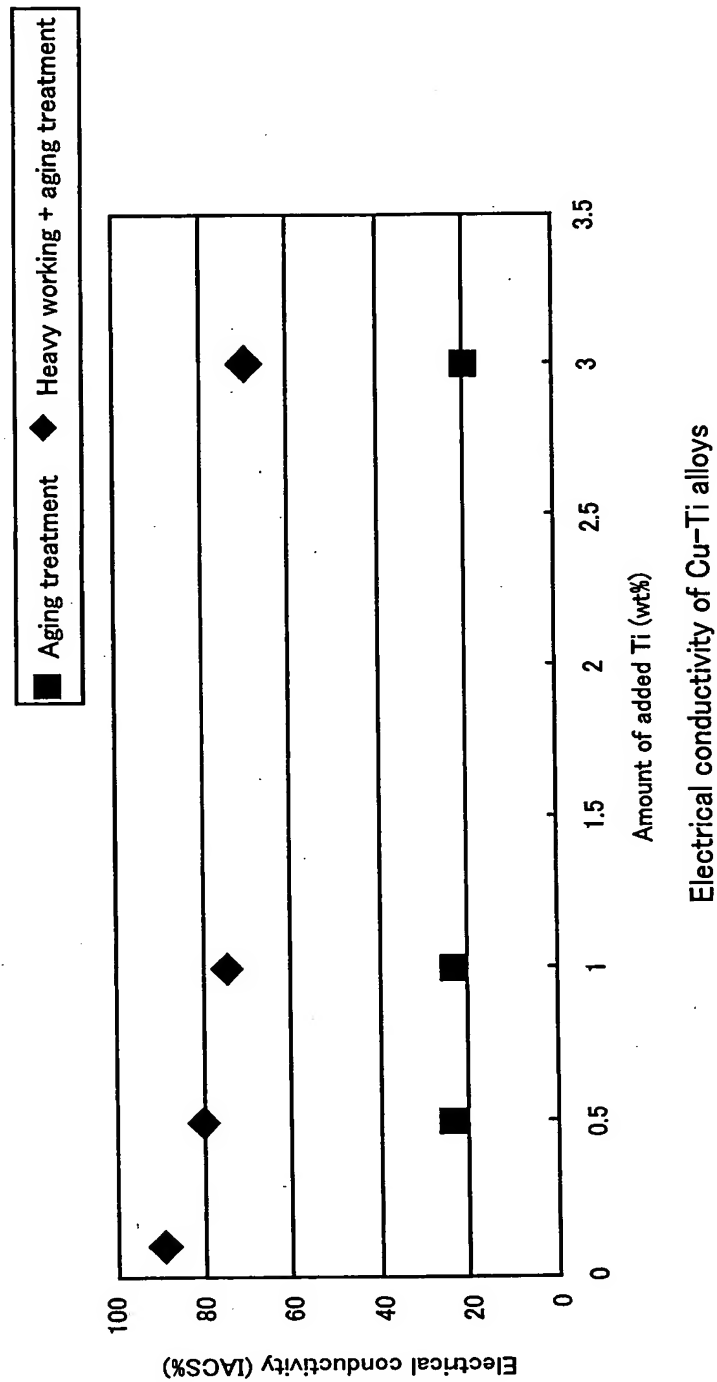


FIG. 10

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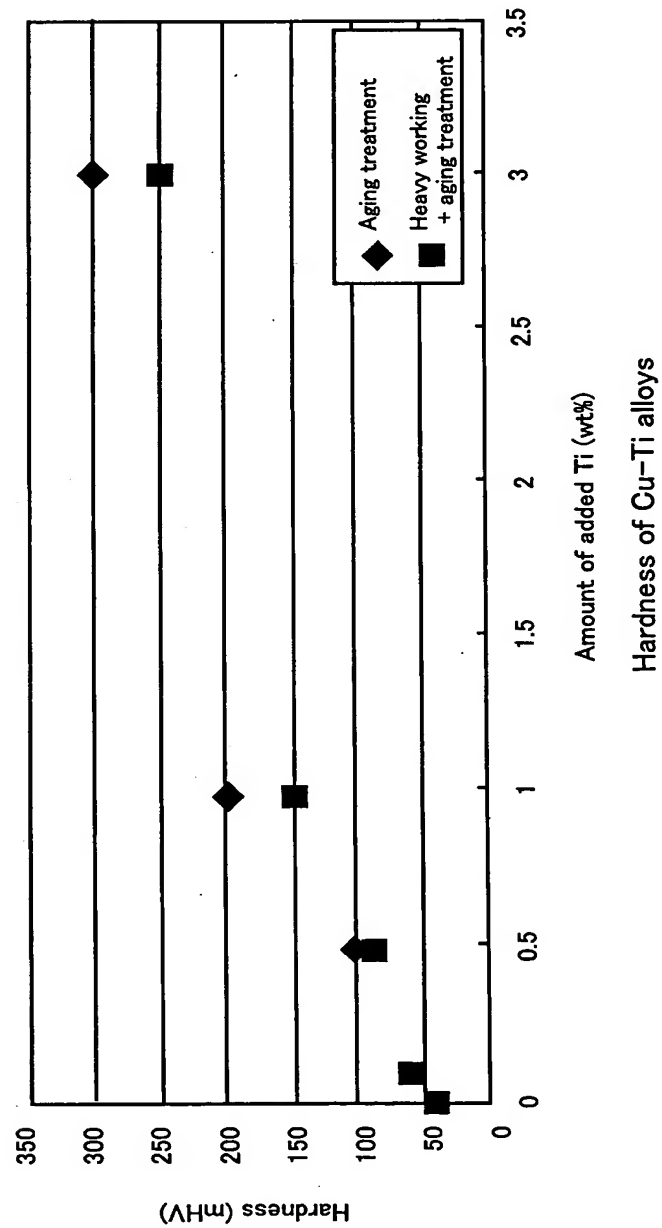


FIG. 11

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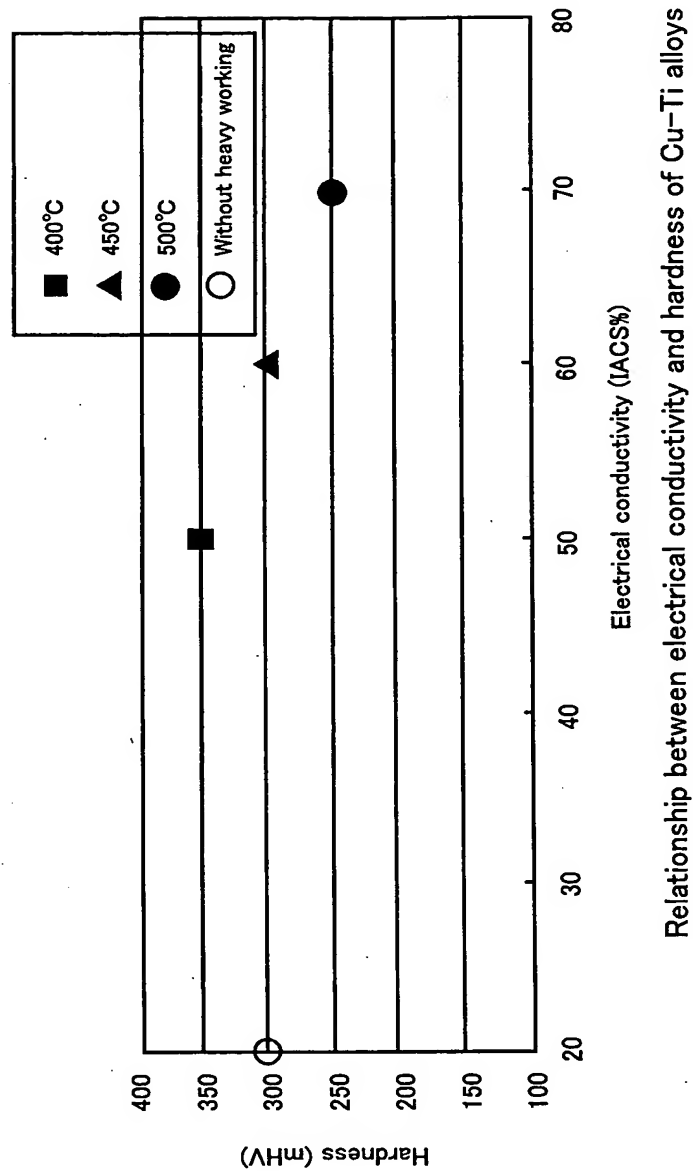
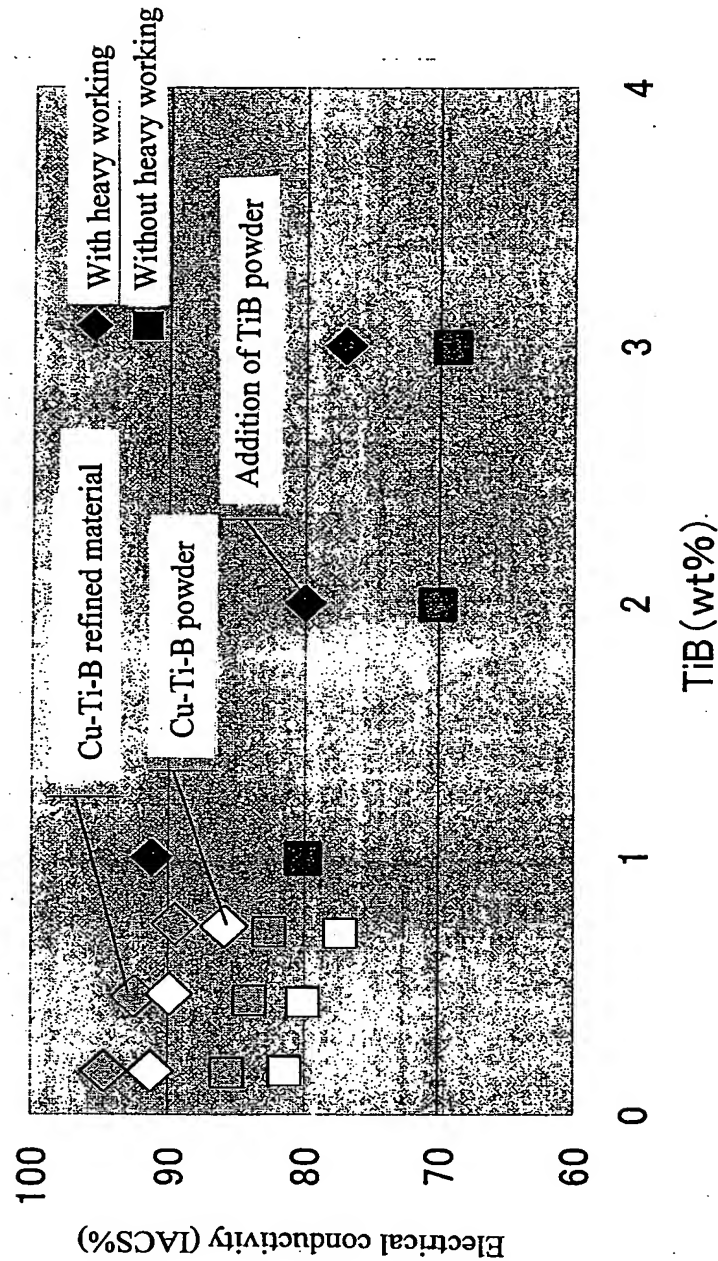


FIG. 12

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FIG. 13



Relationship between methods of adding TiB and electrical conductivity

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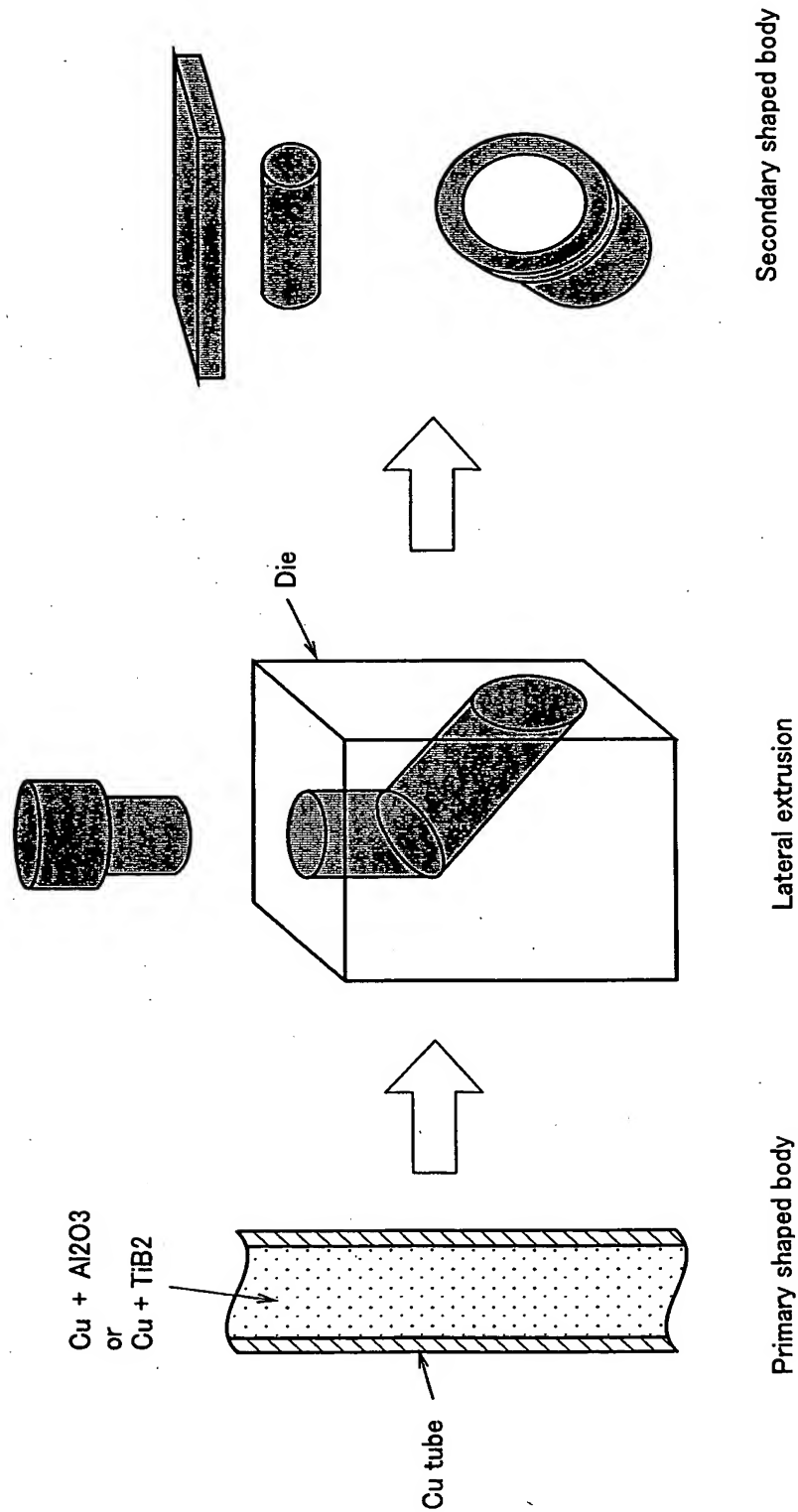
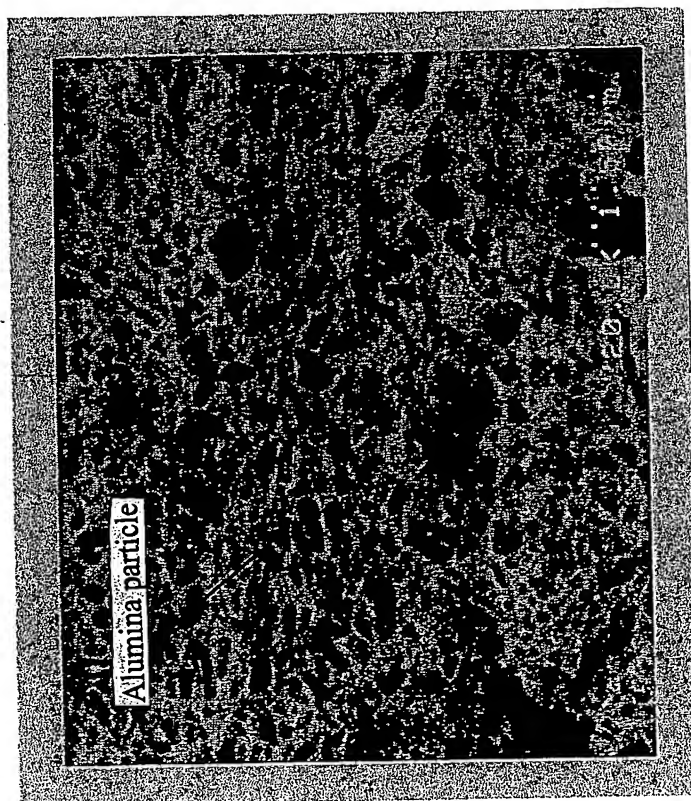
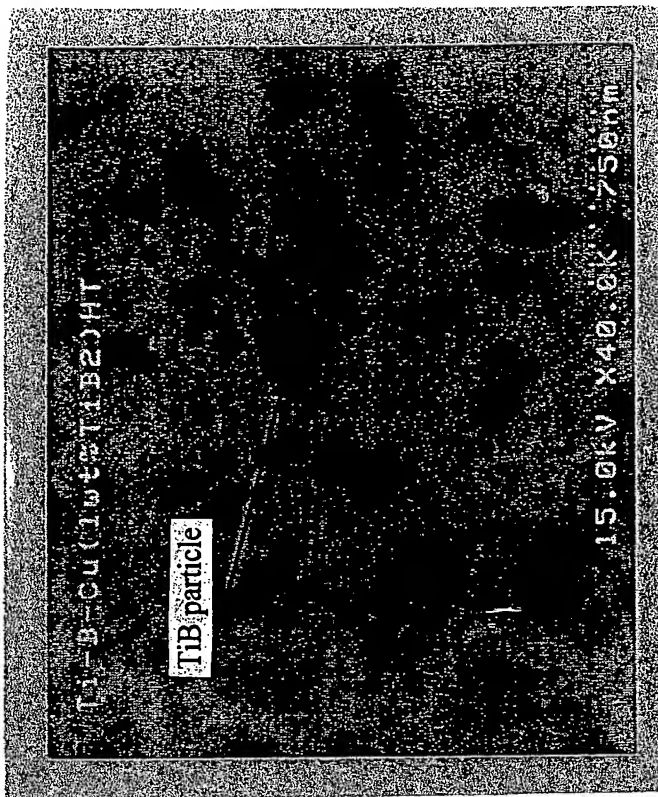


FIG. 14

FIG. 15



(a)



(b)

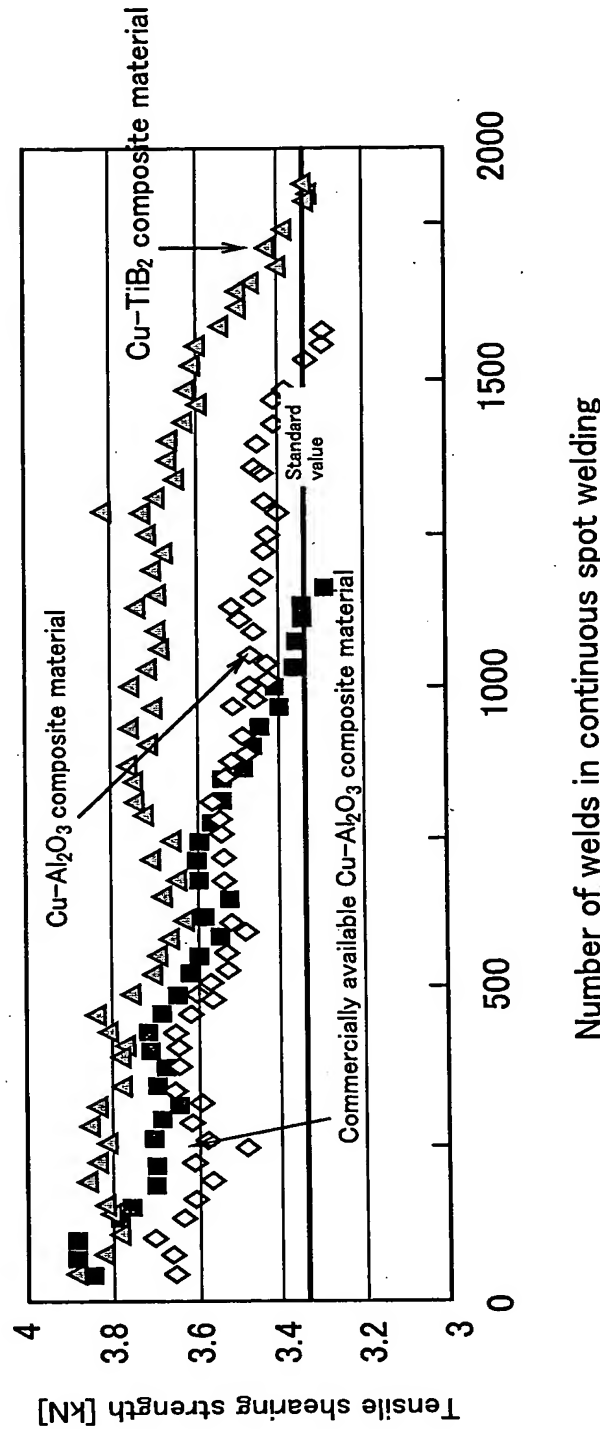


FIG. 16

FIG. 17

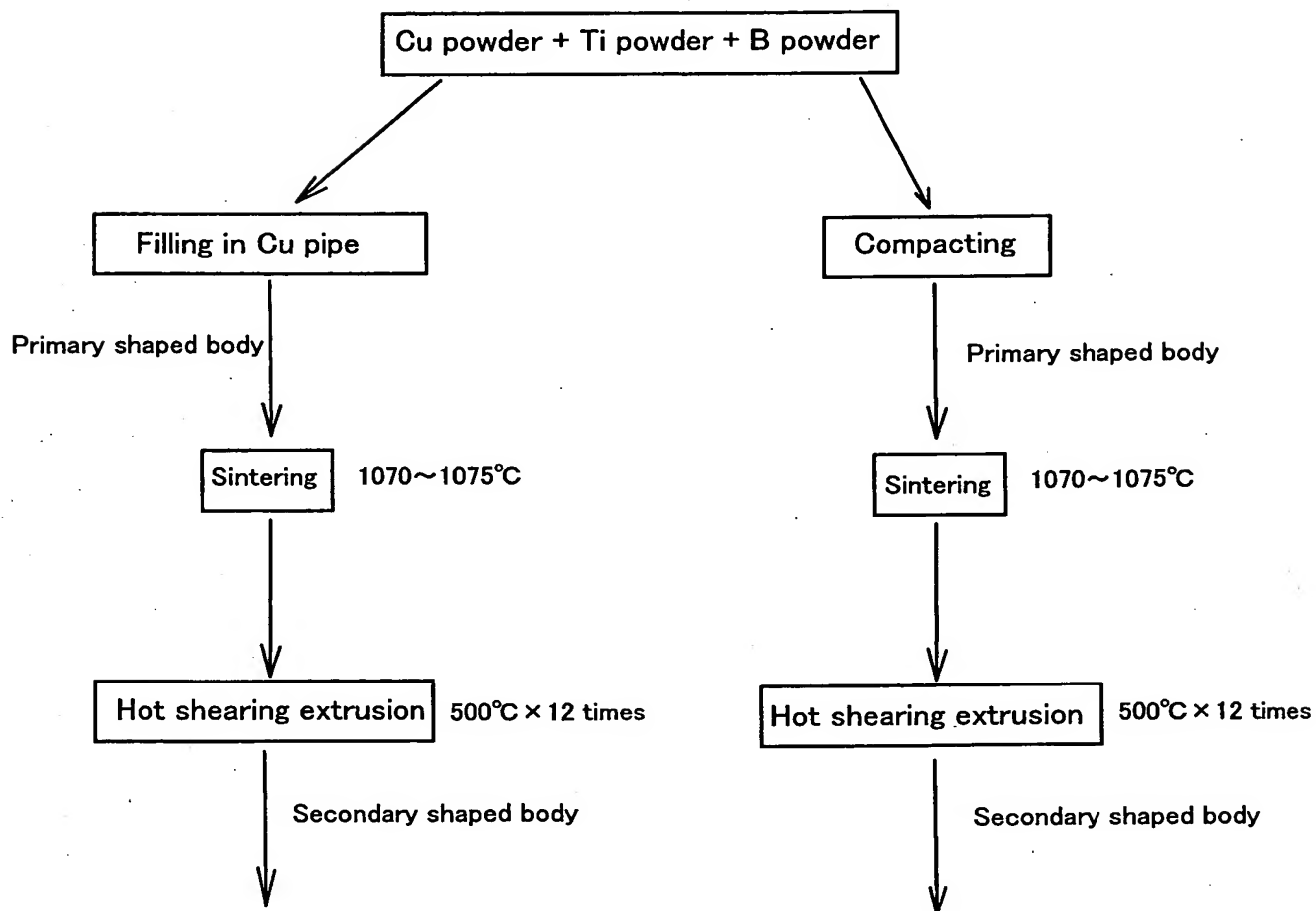
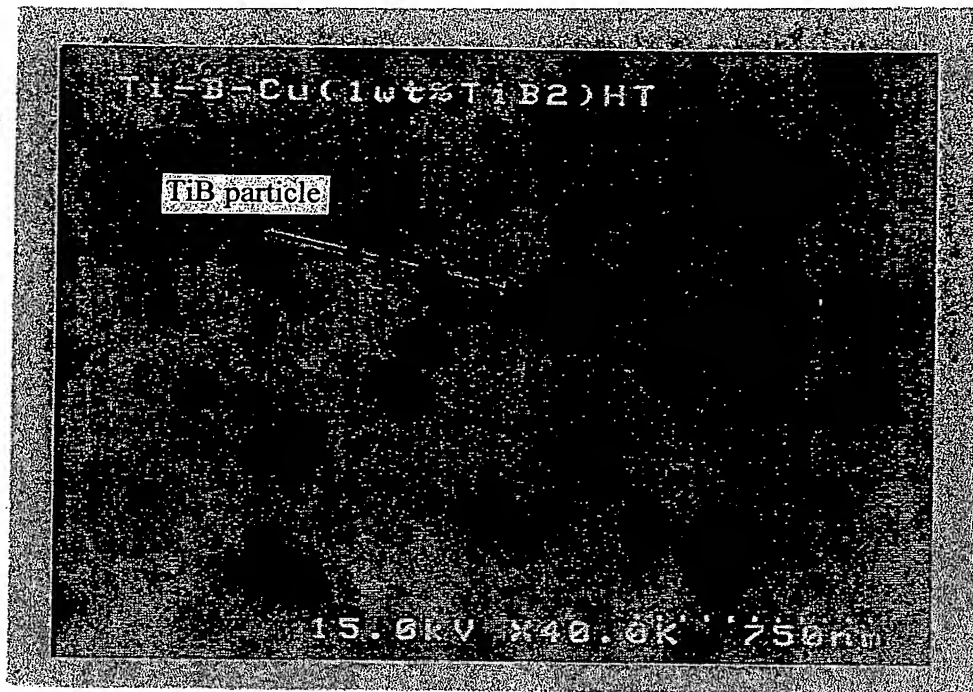
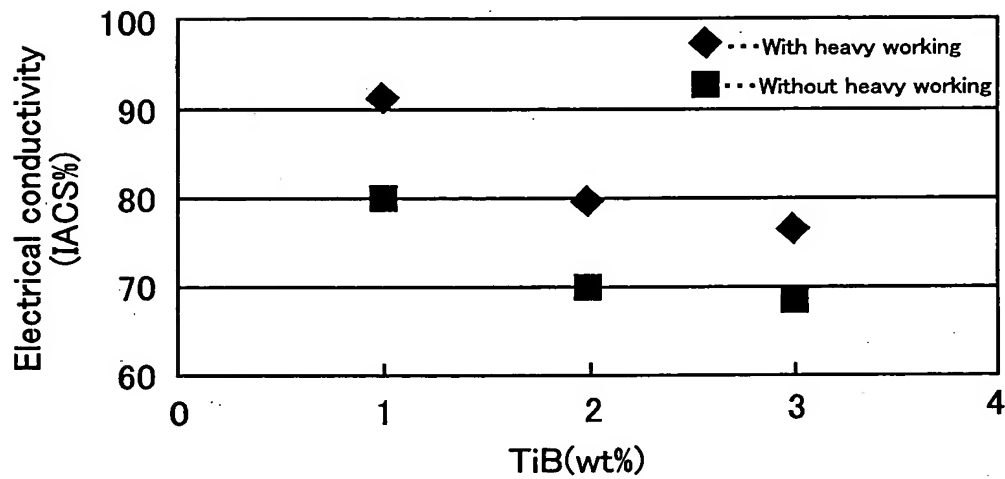


FIG. 18



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FIG. 19



Relationship between heavy working of Cu-TiB
(strain equivalent to 200% elongation
and electrical conductivity

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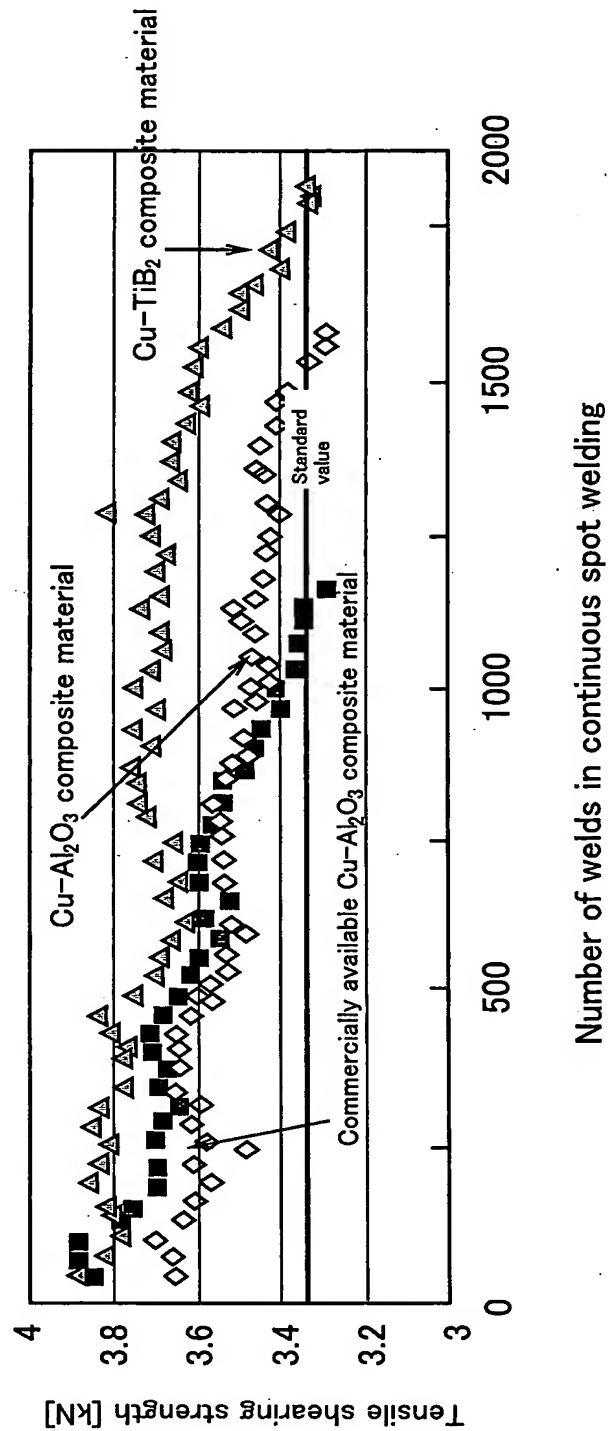


FIG. 20

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